

SYSTEM AND METHOD FOR HIGH PERFORMANCE HEAT SINK  
FOR MULTIPLE CHIP DEVICES

ABSTRACT OF THE DISCLOSURE

5 A custom-molded heat sink corresponds to an individual substrate and includes a heat sink lid having at least one cavity corresponding to at least one die mounted on a substrate. A conductive layer is deposited in the at least one cavity that substantially fills the space between the at least one cavity and the at least one die when the lid is coupled to the substrate.